**AMENDMENT NO.1 OCTOBER 2024**

**TO**

**IS 13730 (PART 35): 2017 SPECIFICATIONS FOR PARTICULAR TYPES OF WINDING WIRES PART 35 SOLDERABLE POLYURETHANE ENAMELLED ROUND COPPER WIRE, CLASS 155, WITH A BONDING LAYER**

This amendment to Indian Standard **IS 13730 (Part 35): 2017** is identical to merged amendment 1 (2019) and amendment 2 (2024) to IEC 60317-35: 2013 issued by International Electrotechnical Commission (IEC).

**National Foreword - Add the following statement to the Foreword:**

This International Standard is to be used in conjunction with IEC 60317-0-1:2013 and its Amendment 1:2019.

**(Page 1 Clause 2)- Replace the existing text by the following text and footnote:**

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies.

For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60317-0-11:2013, *Specifications for particular types of winding wires – Part 0-1: General requirements – Enamelled round copper wire*.

1 There exists a consolidated edition 4.1:2021 that includes IEC 60317-0-1:2013 and its Amendment 1:2019.

**(Page 1 clause 3.1) - Replace the existing text by the following:**

"For the purposes of this document, the terms and definitions given in IEC 60317-0-1 apply.

ISO and IEC maintain terminology databases for use in standardization at the following

addresses:

• IEC Electropedia: available at https://www.electropedia.org/

• ISO Online browsing platform: available at https://www.iso.org/obp"

**(Page 3 Clause 3.2.1)- Replace the existing title and text by the following:**

**3.2.1 Methods of test**

Subclause 3.2.1 of IEC 60317-0-1:2013 and IEC 60317-0-1:2013/AMD1:2019 applies.

In case of inconsistencies between IEC 60317-0-1 and this document, IEC 60317-35 shall prevail.

**(Page 2 Clause 5)-** *Replace the existing text by the following:*

Clause 5 of IEC 60317-0-1:2013 and IEC 60317-0-1:2013/AMD1:2019 applies.

**(Page 3 Clause 17) Replace the content of this clause by the following:**

17.1 General

The temperature of the solder bath shall be (390 ± 5) °C. The surface of the tinned wire shall be smooth and free from holes and enamel residues.

**(Page No. 4 Clause 17.2) Nominal conductor diameters up to and including 0,100 mm**

The maximum immersion time shall be 2 s.

**[Page 4] — Insert the following new clause after 17.2**

17.3 Nominal conductor diameters over 0,100 mm

The maximum immersion time (in seconds) shall be the following multiple of the nominal

conductor diameter (in millimetres) with a minimum of 2 s.

|  |  |
| --- | --- |
| Grade 1B | Grade 2B |
| 12 s/mm | 16 s/mm |